## General Description

The SY89835U is a 2.5 V , high-speed 2 GHz differential Low Voltage Differential Swing (LVDS) 1:2 fanout buffer optimized for ultra-low skew applications. Within device skew is guaranteed to be less than 20ps over supply voltage and temperature. A unique Fail-Safe Input (FSI) protection prevents metastable conditions when no signal is present or when the selected input clock fails to a DC voltage (voltage between the pins of the differential input drops sufficiently below 100 mV ).
The SY89835U is part of Micrel's high-speed clock synchronization family. For applications that require a different I/O combination, consult Micrel's web site, and choose from a comprehensive product line of highspeed, low-skew fanout buffers, translators and clock generators.
Data sheets and support documentation can be found on Micrel's web site at: www.micrel.com.

## Functional Block Diagram



## Features

- Guaranteed AC performance over temperature and voltage:
- DC-to > 3.2Gbps throughput
- 210ps typical propagation delay (IN-to-Q)
- <20ps within-device skew
- <150ps rise/fall times
- Fail Safe Input
- Prevents outputs from oscillating
- Ultra-low jitter design
- $<1 \mathrm{ps}_{\text {RMS }}$ cycle-to-cycle jitter
$-<10 p s_{\text {pp }}$ total jitter
$-<1 \mathrm{ps}_{\mathrm{RMS}}$ random jitter
- <10pspp deterministic jitter
- High-speed LVDS outputs
- $2.5 \mathrm{~V} \pm 5 \%$ power supply operation
- Industrial temperature range: $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$
- Available in 8-pin ( $2 \mathrm{~mm} \times 2 \mathrm{~mm}$ ) MLF ${ }^{\text {TM }}$ package


## Applications

- Clock or data distribution
- SONET clock or data distribution
- Fibre Channel clock or data distribution
- Gigabit Ethernet clock or data distribution


## Markets

- DataCom
- Telecom
- Storage
- ATE
- Precision test and measurement


## Ordering Information ${ }^{(1)}$

| Part Number | Package <br> Type | Operating <br> Range | Package Marking | Lead <br> Finish |
| :--- | :---: | :---: | :---: | :---: |
| SY89835UMG | MLF-8 | Industrial | 835 with Pb-Free <br> bar-line indicator | NiPdAu <br> Pb-Free |
| SY89835UMGTR $^{(2)}$ | MLF-8 | Industrial | 835 with Pb-Free <br> bar-line indicator | NiPdAu <br> Pb-Free |

## Notes:

1. Contact factory for die availability. Dice are guaranteed at $\mathrm{TA}=25^{\circ} \mathrm{C}, \mathrm{DC}$ Electricals only.
2. Tape and Reel.

## Pin Configuration



8-Pin MLF ${ }^{\text {TM }}$ (MLF-8)

## Pin Description

| Pin Number | Pin Name | Pin Function |
| :---: | :---: | :--- |
| 1 | VCC | Positive Power Supply: Bypass with $0.1 \mu \mathrm{~F} / / 0.01 \mu \mathrm{~F}$ low ESR capacitor and place as <br> close to VCC pin as possible. Power supply tolerance is $\pm 5 \%$. |
| 2,3 | IN, /IN | Differential Inputs: This input pair is the differential signal input to the device. Input <br> accepts DC-Coupled differential signals as small as 100mV (200mVPP). The input is <br> internally terminated with 100 between IN and /IN. If the input swing falls below a <br> certain threshold (typically 30mV), the Fail Safe Input (FSI) feature will guarantee a <br> stable output by latching the output to its last valid state. Please refer to the "Input <br> Interface Applications" section for more details. |
| 4 | GND | Ground. GND pins and exposed pad must be connected to the most negative <br> potential of the device ground. |
| 5,6 | /Q1, Q1 <br> /Q0, Q0 | Differential Outputs (LVDS): Normally terminated with $100 \Omega$ across the pair (Q, /Q). <br> See "LVDS Outputs" section, Figure 2a. |

## Truth Table

| IN | IIN | $\mathbf{Q}$ | IQ |
| :---: | :---: | :---: | :---: |
| 0 | 1 | 0 | 1 |
| 1 | 0 | 1 | 0 |

## Absolute Maximum Ratings ${ }^{(\mathbf{1 )}}$

Supply Voltage ( $\mathrm{V}_{\mathrm{cc}}$ ).............................. 0.5 V to +4.0 V
Input Voltage ( $\mathrm{V}_{\text {IN }}$ )........................... -0.5 V to $\mathrm{V}_{\mathrm{cc}}+0.3 \mathrm{~V}$
LVDS Output Current (lout)................................. $\pm 10 \mathrm{~mA}$
Input Current
Source or Sink Current on (IN, /IN) ............... $\pm 50 \mathrm{~mA}$
Lead Temperature (soldering, 20sec.).................. $260^{\circ} \mathrm{C}$


## Operating Ratings ${ }^{(2)}$

Supply Voltage ( $\mathrm{V}_{\text {IN }}$ ) +2.375 V to +2.635 V
Ambient Temperature $\left(T_{A}\right) \ldots . . . . . . . . . . . . . . . ~-~ 40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$
Package Thermal Resistance ${ }^{(3)}$ MLF ${ }^{\text {TM }}$
Still-air $\left(\theta_{\mathrm{JA}}\right)$................................................. $93^{\circ} \mathrm{C} / \mathrm{W}$
Junction-to-board $\left(\Psi_{\mathrm{JB}}\right)$................. $32^{\circ} \mathrm{C} / \mathrm{W}$

## DC Electrical Characteristics ${ }^{(4)}$

$\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{cc}}$ | Power Supply Voltage Range |  | 2.375 | 2.5 | 2.625 | V |
| Icc | Power Supply Current | No load, max. V ${ }_{\text {cc }}$ |  | 50 | 70 | mA |
| $\mathrm{R}_{\text {IIFF_IN }}$ | Differential Input Resistance (IN-to-/IN) |  | 90 | 100 | 110 | $\Omega$ |
| $\mathrm{V}_{\mathrm{H}}$ | Input HIGH Voltage (IN, /IN) |  | 1.2 |  | $\mathrm{V}_{\mathrm{cc}}$ | V |
| $\mathrm{V}_{\text {IL }}$ | Input LOW Voltage (IN, /IN) |  | 0 |  | $\mathrm{V}_{1+}-0.1$ | V |
| $\mathrm{V}_{\mathrm{IN}}$ | Input Voltage Swing (IN, /IN) | see Figure 2c | 0.1 |  | $\mathrm{V}_{\mathrm{cc}}$ | V |
| $\mathrm{V}_{\text {DIFF_IN }}$ | Differential Input Voltage Swing (IIN - /IN\|) | see Figure 2d | 0.2 |  |  | V |
| VIN_FSI | Input Voltage Threshold that Triggers FSI |  |  | 30 | 100 | mV |

## LVDS Outputs DC Electrical Characteristics ${ }^{(4)}$

$\mathrm{V}_{\mathrm{CC}}=+2.5 \mathrm{~V} \pm 5 \%, \mathrm{R}_{\mathrm{L}}=100 \Omega$ across the outputs; $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $V_{\text {OUT }}$ | Output Voltage Swing | See Figure 2c | 250 | 325 |  | mV |
| $V_{\text {DIFF_OUT }}$ | Differential Output Voltage Swing | See Figure 2d | 500 | 650 |  | mV |
| V OCM | Output Common Mode Voltage |  | 1.125 | 1.20 | 1.275 | V |
| $\Delta$ V OCM | Change in Common Mode <br> Voltage |  | -50 |  | 50 | mV |

## Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. $\psi_{\mathrm{JB}}$ and $\theta_{\mathrm{JA}}$ values are determined for a 4-layer board in still-air number, unless otherwise stated.
4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

## AC Electrical Characteristics ${ }^{(5)}$

$V_{C C}=+2.5 \mathrm{~V} \pm 5 \%, R_{L}=100 \Omega$ across the outputs; $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise stated.

| Symbol | Parameter | Condition |  | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{f}_{\text {MAX }}$ | Maximum Frequency | $V_{\text {OUT }}>200 \mathrm{mV}$ | NRZ Data | 3.2 |  |  | Gbps |
|  |  |  | Clock | 2.0 | 3.0 |  | GHz |
| $\mathrm{t}_{\text {PD }}$ | Propagation Delay IN-to-Q | $\begin{aligned} \mathrm{V}_{\mathrm{IN}}: & 100 \mathrm{mV}-200 \mathrm{mV} \\ & >200 \mathrm{mV} \end{aligned}$ |  | $\begin{aligned} & 150 \\ & 100 \end{aligned}$ | $\begin{aligned} & 300 \\ & 210 \end{aligned}$ | $\begin{aligned} & 500 \\ & 400 \end{aligned}$ | ps |
| $\mathrm{t}_{\text {skew }}$ | Within Device Skew | Note 6 |  |  | 5 | 20 | ps |
|  | Part-to-Part Skew | Note 7 |  |  |  | 200 | ps |
| $t_{\text {ditter }}$ | Data Random Jitter | Note 8 |  |  |  | 1 | pS ${ }_{\text {RMS }}$ |
|  | Deterministic Jitter | Note 9 |  |  |  | 10 | pSpp |
|  | Clock Cycle-to-Cycle Jitter | Note 10 |  |  |  | 1 | ps SMS |
|  | Total Jitter | Note 11 |  |  |  | 10 | pspp |
| $\mathrm{tr}_{\mathrm{r}} \mathrm{t}_{\mathrm{f}}$ | Output Rise/Fall Times (20\% to 80\%) | At full output swing. |  | 40 | 75 | 150 | ps |
|  | Duty Cycle | Differential I/O |  | 47 |  | 53 | \% |

## Notes:

5. High-frequency AC parameters are guaranteed by design and characterization.
6. Within device skew is measured between two different outputs under identical input transitions.
7. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and no skew at the edges at the respective inputs.
8. Random jitter is measured with a K 28.7 pattern, measured at $\leq \mathrm{f}_{\text {MAX }}$.
9. Deterministic jitter is measured at 2.5 Gbps with both K 28.5 and $2^{23}-1$ PRBS pattern.
10. Cycle-to-cycle jitter definition: the variation period between adjacent cycles over a random sample of adjacent cycle pairs. $\mathrm{t}_{\text {IITTER_cc }}=\mathrm{T}_{\mathrm{n}}-\mathrm{T}_{\mathrm{n}+1}$, where T is the time between rising edges of the output signal.
11. Total jitter definition: with an ideal clock input frequency of $\leq f_{\text {mAX }}$ (device), no more than one output edge in $10^{12}$ output edges will deviate by more than the specified peak-to-peak jitter value.

## Functional Description

## Fail-Safe Input (FSI)

The input includes a special failsafe circuit to sense the amplitude of the input signal and to latch the outputs when there is no input signal present, or when the amplitude of the input signal drops sufficiently below $100 \mathrm{~m} \mathrm{~V}_{\mathrm{PK}}\left(200 \mathrm{~m} \mathrm{~V}_{\mathrm{PP}}\right)$.

## Input Clock Failure Case

If the input clock fails to a floating, static, or extremely low signal swing, the FSI function will eliminate a
metastable condition and guarantee a stable output signal. No ringing and no undetermined state will occur at the output under these conditions.
Please note that the FSI function will not prevent duty cycle distortion in case of a slowly deteriorating (but still toggling) input signal. Due to the FSI function, the propagation delay will depend upon the rise and fall time of the input signal and on its amplitude. Refer to "Typical Operating Characteristics" for detailed information.

## Timing Diagrams



## Typical Characteristics

$\mathrm{V}_{\mathrm{CC}}=2.5 \mathrm{~V}, G N D=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{IN}}=100 \mathrm{mV}, \mathrm{R}_{\mathrm{L}}=100 \Omega$ across the outputs, $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise stated.


Propagation Delay vs.
Input Rise/Fall Time



INPUT RISE/FALL TIME (ps)

Propagation Delay vs. Input Rise/Fall Time


## Functional Characteristics

$\mathrm{V}_{\mathrm{CC}}=2.5 \mathrm{~V}, G N D=0 \mathrm{~V}, \mathrm{~V}_{\mathbb{I N}}=100 \mathrm{mV}, \mathrm{R}_{\mathrm{L}}=100 \Omega$ across the outputs, $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise stated.


## Input Stage



Figure 1. Simplified Differential Input Buffer

## LVDS Outputs

LVDS specifies a small swing of 325 mV typical, on a nominal 1.20 V common mode above ground. The common mode voltage has tight limits to permit large variations in ground noise between an LVDS driver and receiver. These outputs can drive AC- or DCcoupled differential signals.
The SY89835U can drive long lengths of coaxial cables and FR4 traces. Table 1 below shows typical lengths of cables driven at different clock and data rates.

| Clock/Data <br> Rate | Coaxial Cable <br> Length $^{\mathbf{1 1}}$ | FR4 Cable <br> Length $^{(2)}$ |
| :---: | :---: | :---: |
| 100 MHz | 4.5 m | 1.40 m |
| 622 MHz | 3.5 m | 0.85 m |
| 1.25 Gbps | 3.8 m | 0.80 m |
| 2.50 Gbps | 3.3 m | 0.50 m |

Table 1. Typical Lengths of Coaxial and FR4 Traces

## Notes:

1. Specifications for the center conductor of the coaxial cables used are " $191 / 19 \mathrm{spcw}$ OD .037 inch $\pm 0.001$ ". These are 1 m cables, p/n SB-142 manufactured by Harbour Industries. www.harbourind.com.
2. The FR4 traces are 6.25 mil wide and 6 mil thick. Horizontal distance between adjacent traces is 7.75 mil. These traces are fabricated on a Molex GBX Reference Backplane. www.molex.com.


Figure 2a. LVDS Differential Measurement


Figure 2b. LVDS Common Mode Measurement


Figure 2c. Single-Ended Swing


Figure 2d. Differential Swing

## Input Interface Applications



Figure 3. LVDS Input Interface

Related Product and Support Documents

| Part Number | Function | Data Sheet Link |
| :--- | :--- | :--- |
| SY89542U | 2.5V, 3.2Gbps Dual, Differential 2:1 LVDS <br> Multiplexer with Internal Termination | http://www.micrel.com/_PDF/HBW/sy89542u.pdf |
| SY89543L | 3.3V, 3.2Gbps Dual, Differential 2:1 LVDS <br> Multiplexer with Internal Termination | http://www.micrel.com/_PDF/HBW/sy89543u.pdf |
| SY89544U | 2.5V, 3.2Gbps Differential 4:1 LVDS <br> Multiplexer with Internal Input Termination | http://www.micrel.com/_PDF/HBW/sy89544u.pdf |
|  | MLF TM Manufacturing Guidelines Exposed <br> Pad Application Notes | http://www.amkor.com/products/notes- <br> papers/MLF_appnote_0301.pdf |
| HBW Solutions | New Products and Termination Application <br> Notes | http://www.micrel.com/product-info/products/sy89830u.shtml |

## Package Information



## 8-Pin MLF ${ }^{\text {TM }}$ (MLF-8)

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